

# LED

**SIDE VIEW 0603**  
**0.6 mm HIGH**

## ADVANTAGES

- Reduce spacer thickness and/or eliminate embossing (cost reduction!)
- Market standard tape & reel for automated pick & place machines
- Can be run at lower current levels

## FUNCTIONALITIES

- Specific DESIGN for Printed Conductive Ink

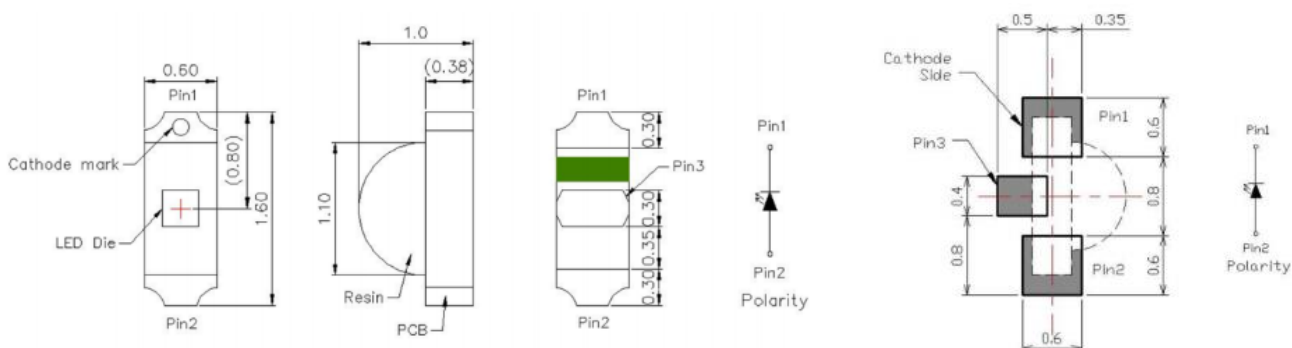
## TECHNICAL DATA

### ELECTRO-OPTICAL CHARACTERISTICS ( $I_F=20\text{mA}$ / $T_a=25^\circ\text{C}$ )

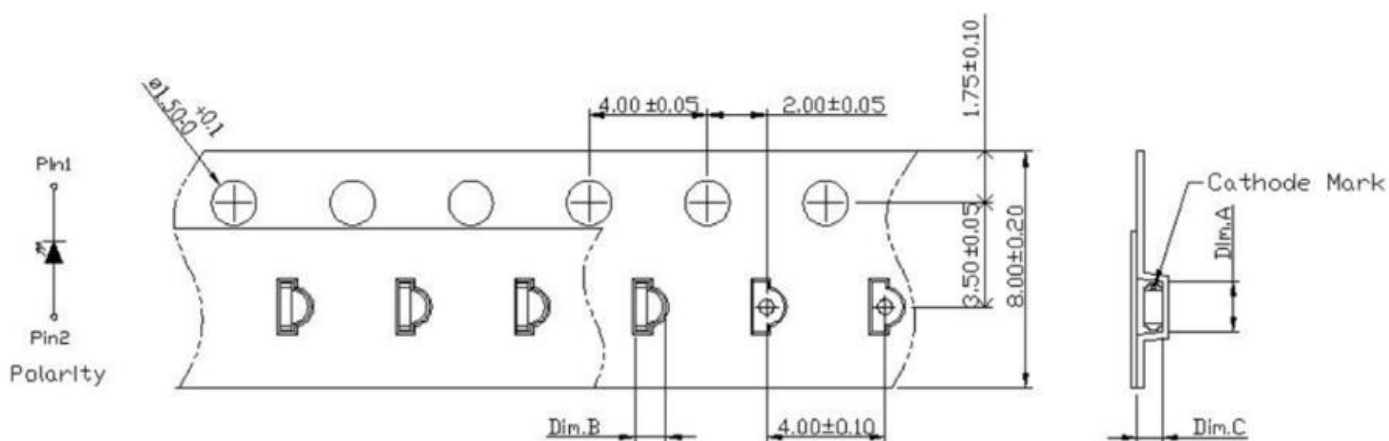
Part Number	Lens Type	Emitting Color	Die Material	Dominant Wavelength $\lambda_d$ (nm)	Luminous Intensity $I_v$ (mcd)		Viewing angle (deg)
					Min.	Typ.	
SR6ZLG60W-06	Water Clear	Green	AllnGaP	571	45	71.5	X=135, Y=120
SR6ZLR60W-06	Water Clear	Red	AllnGaP	631	45	71.5	X=130, Y=120
SR6ZLO60W-06	Water Clear	Orange	AllnGaP	605	45	71.5	X=135, Y=120
SR6ZLY60W-06	Water Clear	Yellow	AllnGaP	589	45	71.5	X=135, Y=120
SR6ZLB60W-06	Water Clear	Blue	InGaN	470	45	71.5	X=140, Y=120
SR6ZLW60D-06	Yellow Diffused	White	InGaN	-	226	330	X=140, Y=120

### PACKAGE DIMENSION & RECOMMENDED SOLDER PATTERN

Mono-color type



### CARRIER TAPE DIMENSION



Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.72 +0.1-0.05	1.05 +0.1-0.05	0.85±0.10	4K

## TECHNICAL DATA

### PRODUCT CHARACTERISTICS (ABSOLUTE MAXIMUM RATINGS)

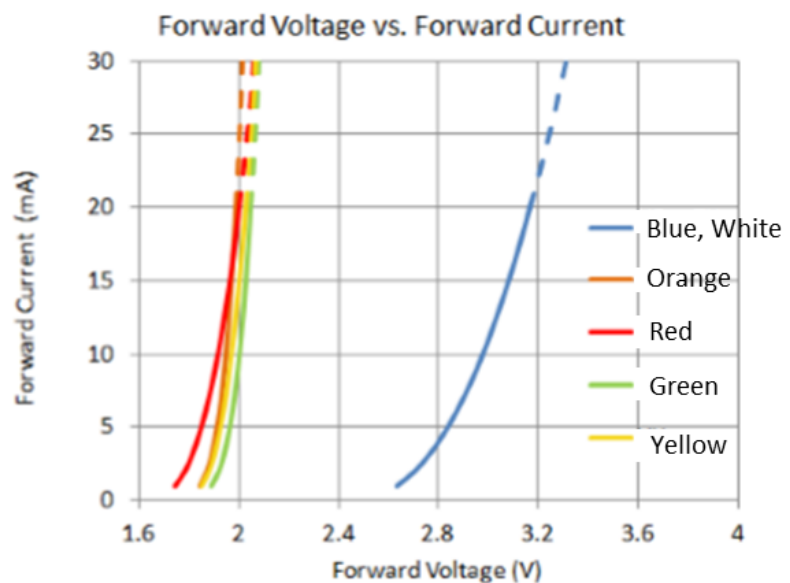
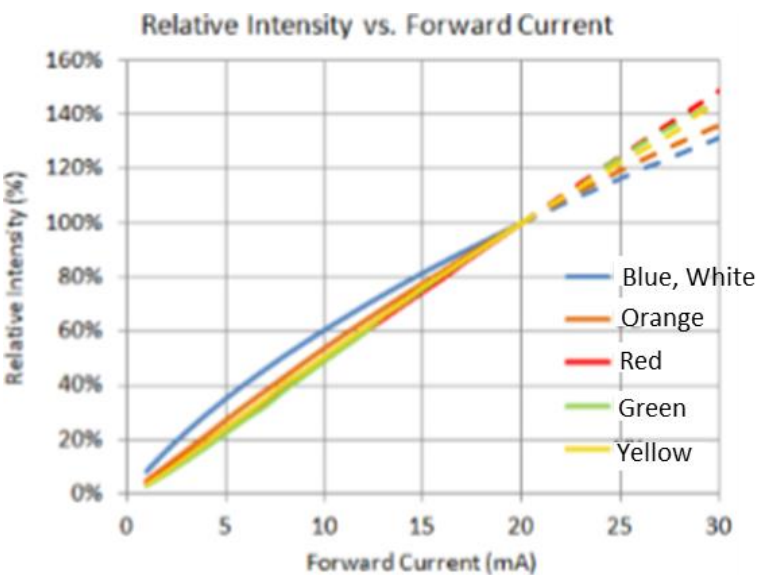
	Red / Orange / Yellow / Green	Blue	White
Reverse voltage $V_R$	5V		
Forward current $I_F$	20 mA	20 mA	20 mA
Peak Forward Current $I_{FP}$ (Duty 1/10 @ 1KHz)	40 mA	60 mA	60 mA
Power Dissipation $P_d$	48 mW	78 mW	66 mW
Electrostatic Discharge (ESD)	2000 V	200 V	200 V
Operating temperature $T_{opr}$	-40°C to +85°C		
Storage temperature $T_{stg}$	-40°C to +100°C		
Soldering temperature $T_{sol}$	217°C for 60~150 sec. 260°C for 10sec Max.		

WARNING

Tolerances:

- Luminous Intensity ( $I_v$ ):  $\pm 11\%$
- Dominant Wavelength ( $\lambda_d$ ):  $\pm 1\text{nm}$
- Forward Voltage ( $V_f$ ):  $\pm 0.1\text{V}$

### TYPICAL ELECTRO-OPTICAL CHARACTERISTICS CURVES



## OTHER INFORMATION

### PRECAUTIONS FOR USE

WARNING

#### Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. **ESD precaution must be taken during design and assembly**. If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.